

SOD323 Plastic-Encapsulate Diodes

Small Signal Fast Switching Diodes

Features

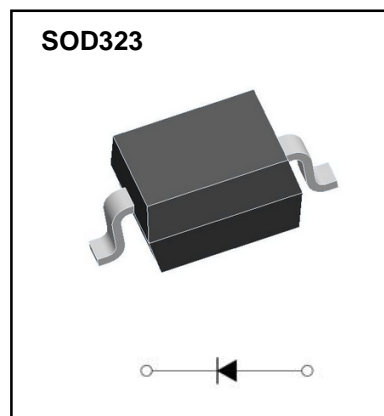
- Low Reverse Current
- Surface Mount Package Ideally Suited for Automatic Insertion
- Fast Switching Speed
- For General Purpose Switching Applications

Applications

- Extreme fast switches

Marking

- BAV19WS: A8
- BAV20WS: T2
- BAV21WS: T3



Limiting Values (Absolute Maximum Rating)

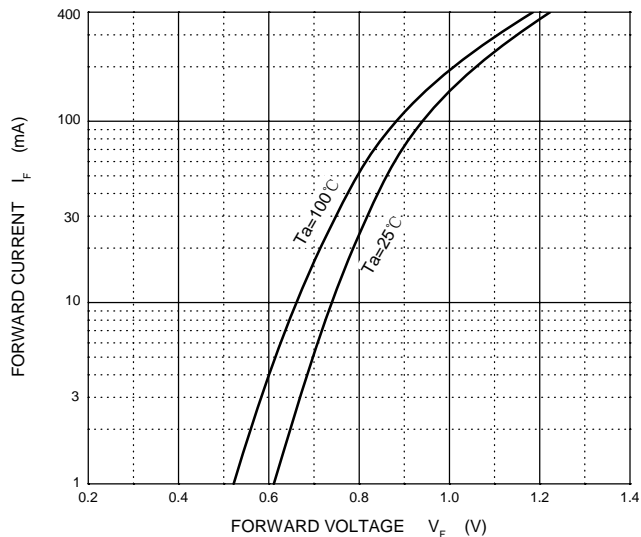
Symbol	Parameter	Value			Unit
		BAV19WS	BAV20WS	BAV21WS	
V_{RM}	Non-Repetitive Peak Reverse Voltage	120	200	250	V
V_{RRM}	Peak Repetitive Reverse Voltage	100	150	200	V
V_{RWM}	Working Peak Reverse Voltage				
$V_{R(RMS)}$	RMS Reverse Voltage	71	106	141	V
I_O	Average Rectified Output Current	200			mA
I_{FSM}	Non-repetitive Peak Forward Surge Current @ t=8.3ms	2.0			A
P_D	Power Dissipation	250			mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	500			°C/W
T_j	Junction Temperature	150			°C
T_{stg}	Storage Temperature	-55~+150			°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

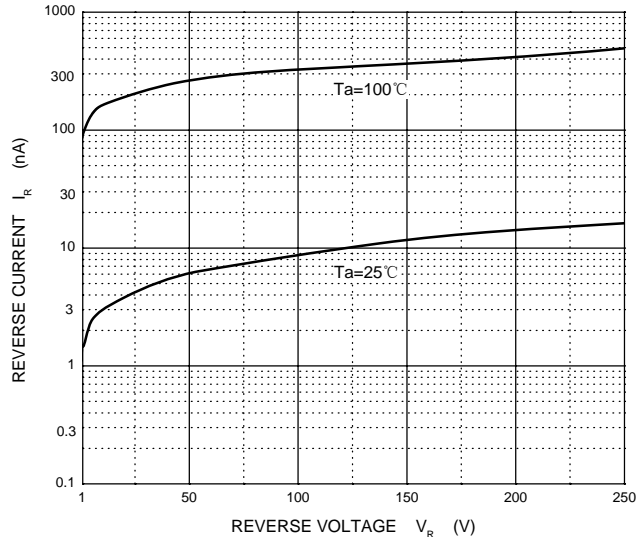
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse current	I_R	$V_R=100\text{V}$	BAV19WS		0.1	uA
		$V_R=150\text{V}$	BAV20WS		0.1	
		$V_R=200\text{V}$	BAV21WS		0.1	
Forward voltage	V_F	$I_F=100\text{mA}$			1	V
		$I_F=200\text{mA}$			1.25	
Total capacitance	C_{tot}	$V_R=0\text{V}, f=1\text{MHz}$			5	pF
Reverse recovery time	t_{rr}	$I_F=I_R=30\text{mA}, I_{rr}=0.1 \cdot I_R, R_L=100\Omega$			50	ns

Typical Characteristics

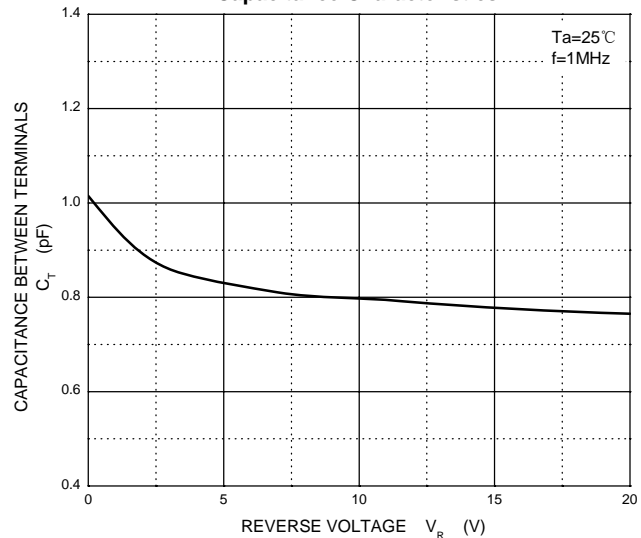
Forward Characteristics



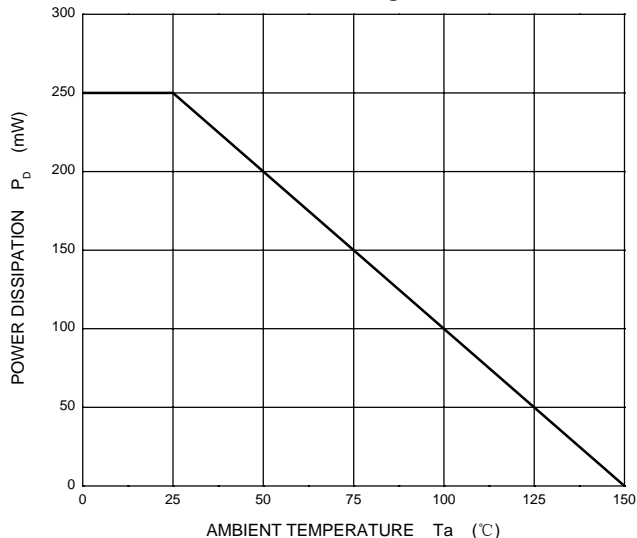
Reverse Characteristics



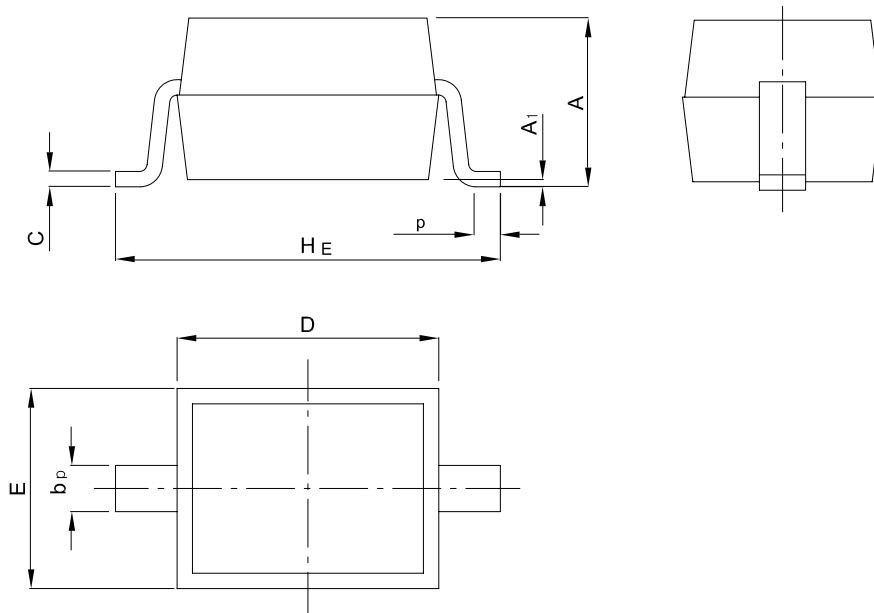
Capacitance Characteristics



Power Derating Curve

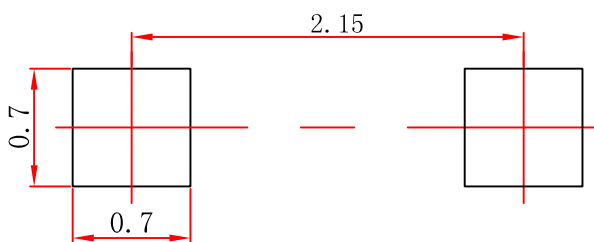


SOD323 Package Outline Dimensions



UNIT	A	bp	C	D	E	HE	A1	Lp
mm	1.20	0.40	0.15	1.80	1.35	2.80	0.10	0.50
	0.80	0.25	0.10	1.60	1.15	2.30	0.01	0.20

SOD323 Suggested Pad Layout



Note:

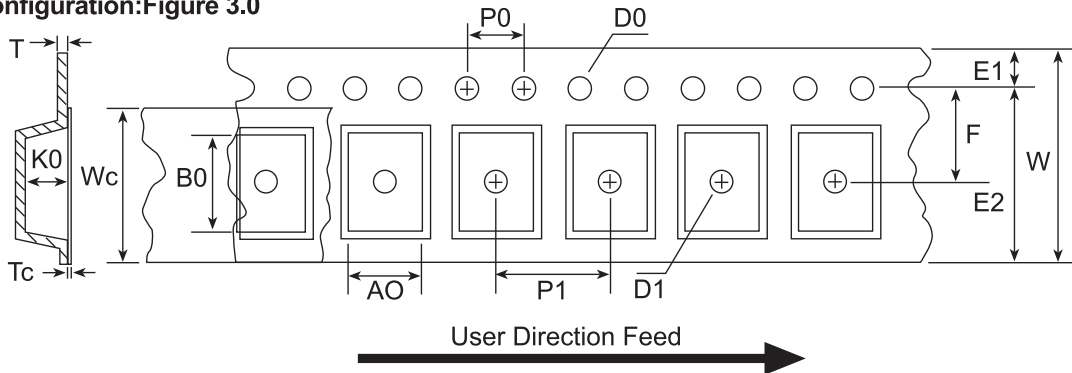
1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSHD does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-SOD323

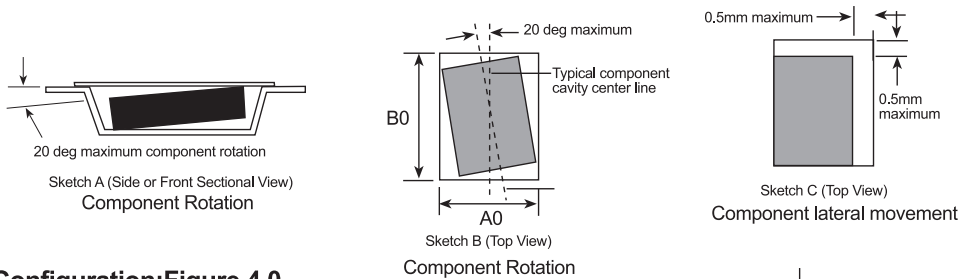
SOD323 Embossed Carrier Tape Configuration: Figure 3.0



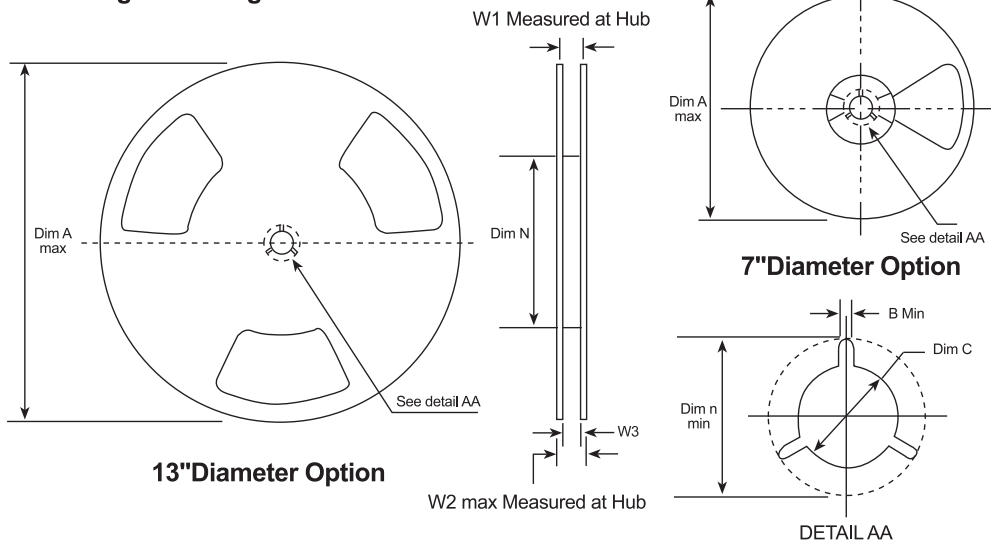
Dimensions are millimeter

Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOD323 (8mm)	1.46 +/-0.10	2.9 +/-0.10	8.0 +/-0.3	1.50 +/-0.125	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.10	4.0 +/-0.10	1.25 +/-0.10	0.25 +/-0.020	5.2 +/-0.20	0.06 +/-0.02

Notes: A0, B0 and K0 dimensions are determined with respect to the EW Jeced RS-481 rotational and lateral movement requirements (see sketches A, B and C).



SOD323 Reel Configuration: Figure 4.0



Dimensions are in inches and millimeter

Type Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	2.165 55	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9
8mm	13" Dia	13.00 330	0.059 1.5	512+0.020/-0.008 13+0.5/-0.2	0.795 20.0	4.00 100	0.331+0.059/-0.000 8.4+1.5/0	0.567 14.4	0.311-0.429 7.9-10.9